



Product Change Notification



Product Group: Vishay Siliconix/ July 1, 2016/PCN SIL-0162016 Rev 0

Vishay Siliconix Announces A Revised Bond Process for the VP1008B, VP0808B and VP0808B-E3

DESCRIPTION OF CHANGE: Vishay Siliconix announces the update to the wire bond process for 2 commercial hermetic parts assembled in Cirtek, Philippines. The change is moving from 1-3mil bond wire to 2-1.25mil bond wires. The change is being made as the subcontractor is limited to 1.25mil aluminum wire.

Please note that this change has successfully passed all qualification tests and does not affect any electrical characteristic of the devices.

CLASSIFICATION OF CHANGE: Material set conversion

REASON FOR CHANGE: Part of continued quality improvement program.

EXPECTED INFLUENCE ON QUALITY/RELIABILITY/PERFORMANCE: No effect on quality, reliability or electrical performance. No change in form, fit or function.

PRODUCT Category: MOSFETs

PART NUMBERS/SERIES/FAMILIES AFFECTED:

VP0808B, VP0808B-E3, VP1008B

VISHAY BRAND(s): Vishay Siliconix

TIME SCHEDULE: Q3, 2016.

SAMPLE AVAILABILITY: Please contact your regional Vishay Sales office for sample availability.

PRODUCT IDENTIFICATION: There will be no change to part numbering.

QUALIFICATION RESULTS: Available upon request

This PCN is considered approved, without further notification.

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